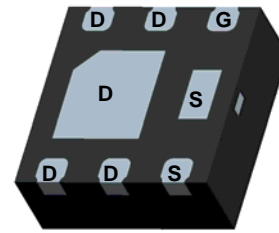
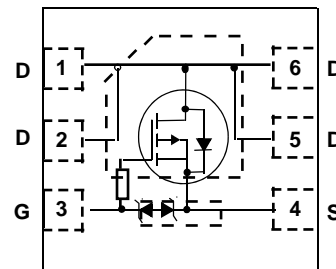


WPM2065
Single P-Channel, -20V, -6.9A, Power MOSFET
[Http://www.sh-willsemi.com](http://www.sh-willsemi.com)

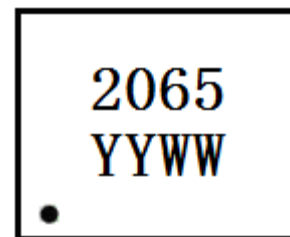
V _{DS} (V)	Typical R _{ds(on)} (Ω)
-20	0.017@ V _{GS} =-4.5V
	0.022@ V _{GS} =-2.5V
	0.032@ V _{GS} =-1.8V
ESD Rating: 4000V HBM	


DFN2X2-6L
Descriptions

The WPM2065 is P-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent R_{DS (ON)} with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit. Standard Product WPM2065 is Pb-free and Halogen-free.


Pin configuration (Top view)
Features

- Trench Technology
- Supper high density cell design
- Excellent ON resistance for higher DC current
- Extremely Low Threshold Voltage
- HBM ESD protection > 4kV
- Small package DFN2X2-6L



2065 = Device Code
YY = Year
WW = Week

Marking
Applications

- Driver for Relay, Solenoid, Motor, LED etc.
- DC-DC converter circuit
- Power Switch
- Load Switch
- Charging

Order information

Device	Package	Shipping
WPM2065-6/TR	DFN2X2-6L	3000/Reel&Tape

Absolute Maximum ratings

Parameter		Symbol	10 S	Steady State	Unit
Drain-Source Voltage		V_{DS}	-20		V
Gate-Source Voltage		V_{GS}	± 8		
Continuous Drain Current ^{a d}	$T_A=25^\circ\text{C}$	I_D	-6.9	-6.2	A
	$T_A=70^\circ\text{C}$		-5.5	-5.0	
Maximum Power Dissipation ^{a d}	$T_A=25^\circ\text{C}$	P_D	1.7	1.4	W
	$T_A=70^\circ\text{C}$		1.1	0.9	
Continuous Drain Current ^{b d}	$T_A=25^\circ\text{C}$	I_D	-5.5	-4.4	A
	$T_A=70^\circ\text{C}$		-4.4	-3.5	
Maximum Power Dissipation ^{b d}	$T_A=25^\circ\text{C}$	P_D	1.1	0.7	W
	$T_A=70^\circ\text{C}$		0.7	0.4	
Pulsed Drain Current ^c		I_{DM}	-28		A
Operating Junction Temperature		T_J	-55 to 150		$^\circ\text{C}$
Lead Temperature		T_L	260		$^\circ\text{C}$
Storage Temperature Range		T_{stg}	-55 to 150		$^\circ\text{C}$

Thermal resistance ratings

Parameter		Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance ^a	$t \leq 10 \text{ s}$	$R_{\theta JA}$	57	72	$^\circ\text{C/W}$
	Steady State		71	90	
Junction-to-Ambient Thermal Resistance ^b	$t \leq 10 \text{ s}$	$R_{\theta JA}$	89	115	
	Steady State		126	181	
Junction-to-Case Thermal Resistance		$R_{\theta JC}$	34	44	

a Surface mounted on FR-4 Board using 1 square inch pad size, 1oz copper

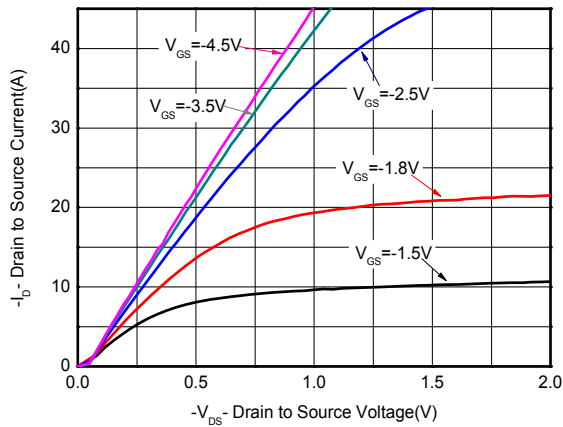
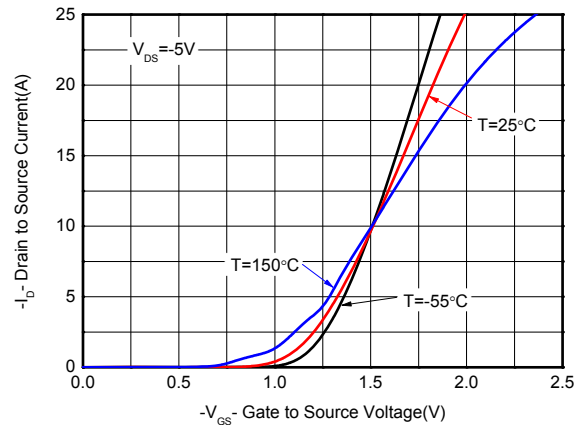
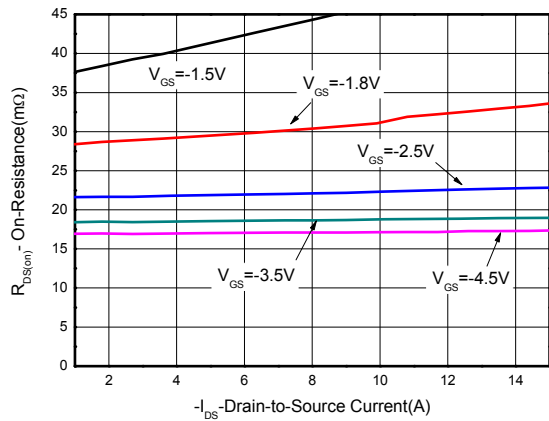
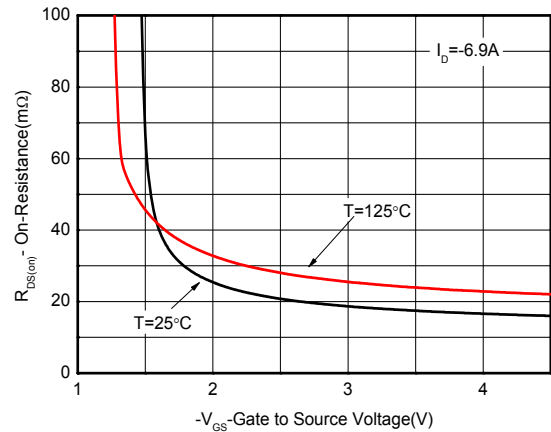
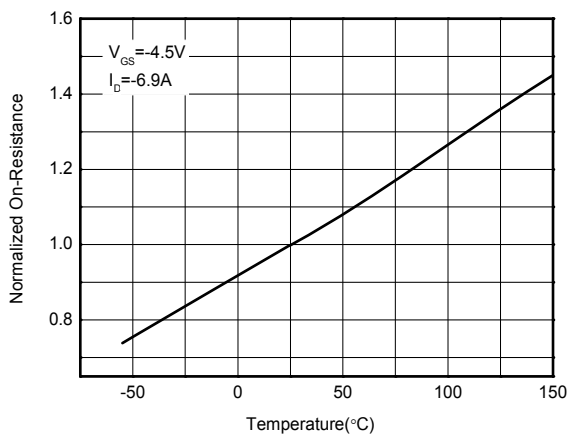
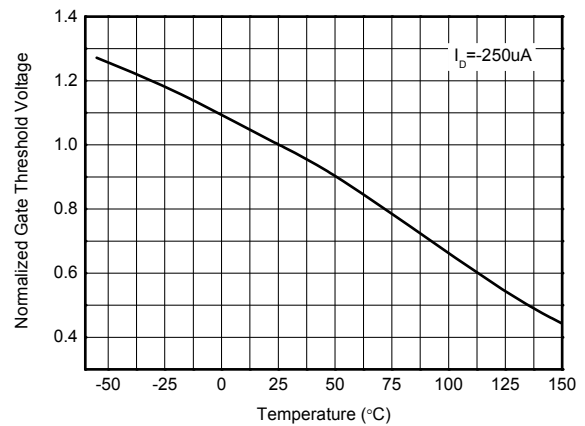
b Surface mounted on FR-4 board using minimum pad size, 1oz copper

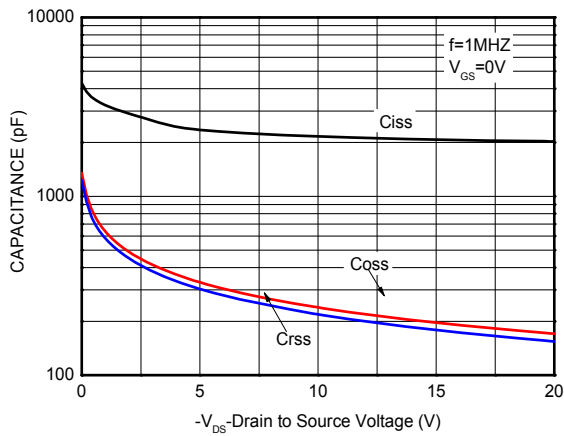
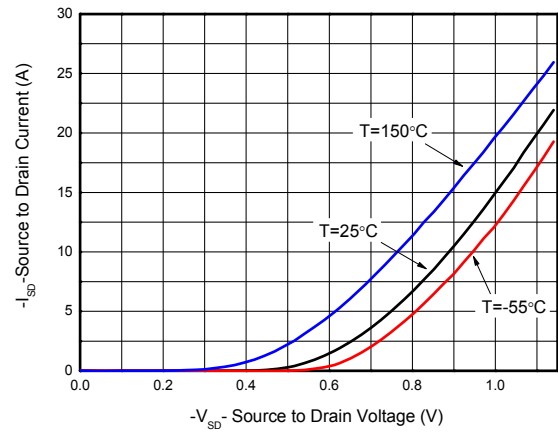
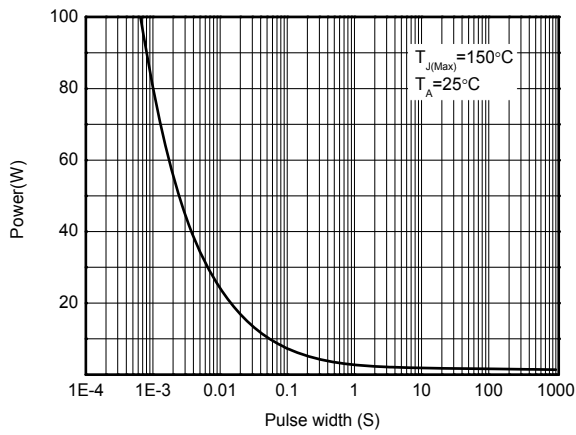
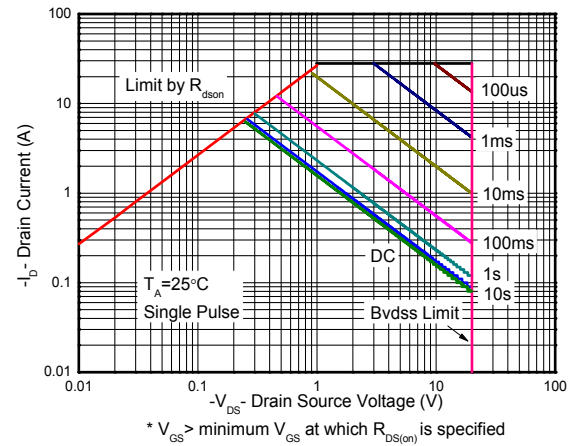
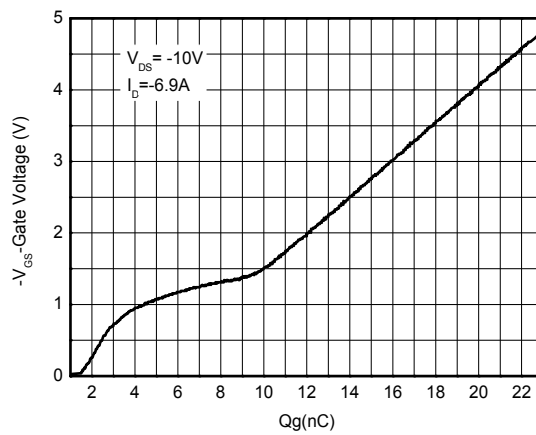
c Pulse width < 380 μs , Duty Cycle < 2%

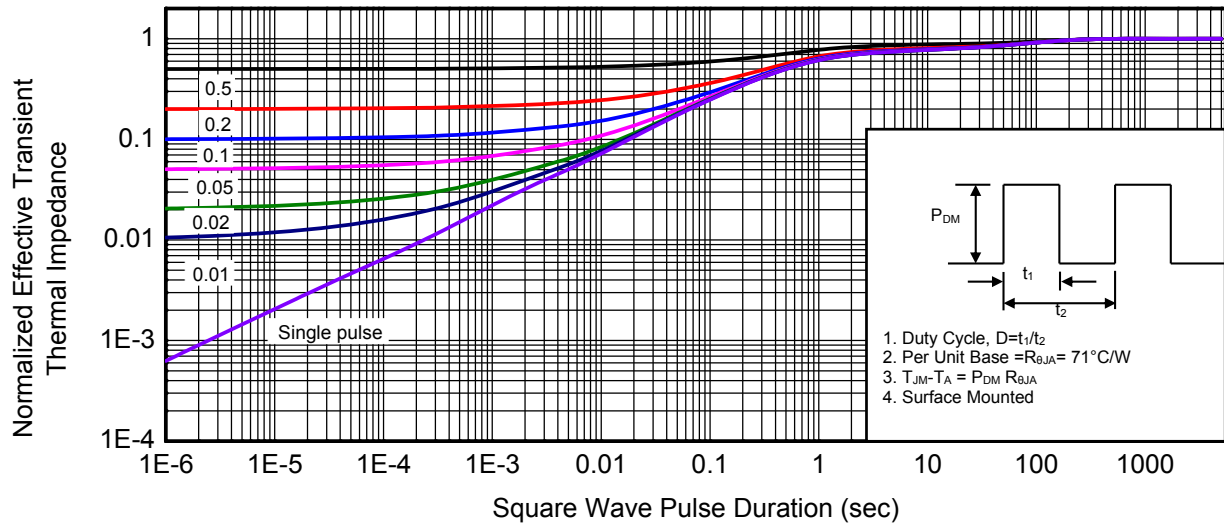
d Maximum junction temperature $T_J=150^\circ\text{C}$.

Electronics Characteristics (Ta=25°C, unless otherwise noted)

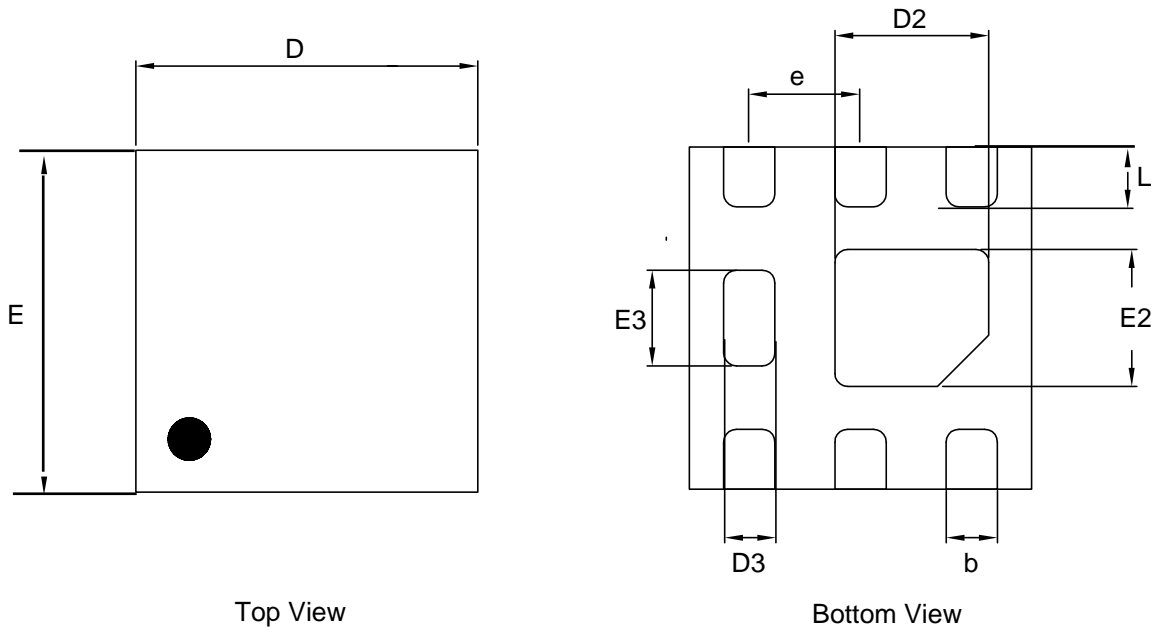
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_D = -250\mu A$	-20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -16V, V_{GS} = 0V$			-1	μA
Gate-to-source Leakage Current	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 8V$			± 5	μA
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = -250\mu A$	-0.45	-0.65	-1.0	V
Drain-to-source On-resistance ^{b, c}	$R_{DS(on)}$	$V_{GS} = -4.5V, I_D = -6.9A$		17	24	m Ω
		$V_{GS} = -2.5V, I_D = -6.1A$		22	29	
		$V_{GS} = -1.8V, I_D = -5.3A$		32	45	
Forward Trans conductance	g_{fs}	$V_{DS} = -5.0V, I_D = -6.9A$		50		S
CAPACITANCES, CHARGES						
Input Capacitance	C_{ISS}	$V_{GS} = 0V,$ $f = 1.0\text{ MHz},$ $V_{DS} = -10V$		2026		pF
Output Capacitance	C_{OSS}			225		
Reverse Transfer Capacitance	C_{RSS}			201		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = -4.5V,$ $V_{DD} = -10V,$ $I_D = -6.9A$		23		nC
Threshold Gate Charge	$Q_{G(TH)}$			2.5		
Gate-to-Source Charge	Q_{GS}			4		
Gate-to-Drain Charge	Q_{GD}			6		
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	$t_d(ON)$	$V_{GS} = -4.5V,$ $V_{DD} = -10V,$ $R_L = 3\Omega,$ $R_G = 6\Omega$		40		ns
Rise Time	t_r			76		
Turn-Off Delay Time	$t_d(OFF)$			284		
Fall Time	t_f			244		
BODY DIODE CHARACTERISTICS						
Forward Voltage	V_{SD}	$V_{GS} = 0V, I_S = -6.9A$		-0.8	-1.5	V

Typical Characteristics (Ta=25°C, unless otherwise noted)

Output characteristics

Transfer characteristics

On-Resistance vs. Drain current

On-Resistance vs. Gate-to-Source voltage

On-Resistance vs. Junction temperature

Threshold voltage vs. Temperature


Capacitance

Body diode forward voltage

Single pulse power

Safe operating power

Gate charge Characteristics



Transient thermal response (Junction-to-Ambient)

Package outline dimensions
DFN2X2-6L


Top View

Bottom View

Side View

Symbol	Dimensions in millimeter		
	Min.	Typ.	Max.
A	0.70	0.75	0.80
A1	0.00	-	0.05
A3	0.203 Ref.		
D	1.95	2.00	2.05
E	1.95	2.00	2.05
D2	0.85	0.90	0.95
E2	0.75	0.80	0.85
D3	0.25	0.30	0.35
E3		0.56	
b	0.25	0.30	0.35
L	0.30	0.35	0.40
e	0.65 BSC.		